

All parts are screened per MIL-PRF-19500, JANTX Level and the device detail specification. All testing is performed at room temperature, unless indicated otherwise. For testing at high and low temperatures, Group A testing is required.

	<b>Test</b>	<b>Method</b>	<b>Conditions / Notes</b>
<b>1</b>	<b>Temperature Cycling</b>	<i>MIL-STD-750 Method 1051</i>	Test condition C or maximum storage temperature, whichever less. 20 cycles, 10 minutes per extreme.
<b>2</b>	<b>Interim Electrical Testing</b>		25°C static parameters per device detail specification.
<b>3</b>	<b>Power Burn-in</b>	<i>MIL-STD-750 Method 1042</i>	160 hours minimum at 125°C.
<b>4</b>	<b>Final Electrical Testing</b>		25°C static parameters per device detail specification.
<b>5</b>	<b>Delta Calculation</b>		Per device detail specification.
<b>6</b>	<b>PDA Calculation</b>		10 percent defective allowed.
<b>7</b>	<b>Seal Test Fine Leak</b>	<i>MIL-STD-750 Method 1071</i>	Condition G or H.
<b>8</b>	<b>Seal Test Gross Leak</b>	<i>MIL-STD-750 Method 1071</i>	Condition C. No bubbles present.

**Notes:**

1. Testing varies in accordance with the device detail specification.
2. Specific customer testing needs may be accommodated into any testing flow (selection tests, temperature requirements, special tests).